

## PCB Shelf Life

Surface Finishing	Vacuum Packing	Storage condition		After open package
		Temp.	Relative Humidity	
HASL (Lead-free)	12 months	20-30°C	< 60%	1. First SMT process completed within 8 hours after package open. 2. Hold time prior to Second SMT process 24 hours.
HASL (Tin Lead)	12 months	20-30°C	< 60%	1. First SMT process completed within 8 hours after package open. 2. Hold time prior to Second SMT process 24 hours.
OSP	6 months	20-30°C	< 60%	1. First SMT process completed within 8 hours after package open. 2. Hold time prior to Second SMT process 8 hours.
Immersion gold	12 months	20-30°C	< 60%	1. First SMT process completed within 8 hours after package open. 2. Hold time prior to Second SMT process 24 hours.
Immersion Silver	6 months	20-30°C	< 60%	1. First SMT process completed within 8 hours after package open. 2. Hold time prior to Second SMT process 24 hours.
Immersion Tin	6 months	20-30°C	< 60%	1. First SMT process completed within 8 hours after package open. 2. Hold time prior to Second SMT process 24 hours.

### Recommendation/ Precaution:

After 3 months need to re-bake or solderability test

A.) The baking should be done when exceeding three months storage before assembly. After baking, the entire assembly process should be done within 48 hrs. The remaining PCBs should be kept in the well-sealed plastic bag to prevent moisture absorption and they should be used within one week.

B.) The baking is recommended to be baked every three months within one year but after baking, they shall be kept in properly vacuum-sealed plastic bag. ( ※ see above for the re-bake conditions )